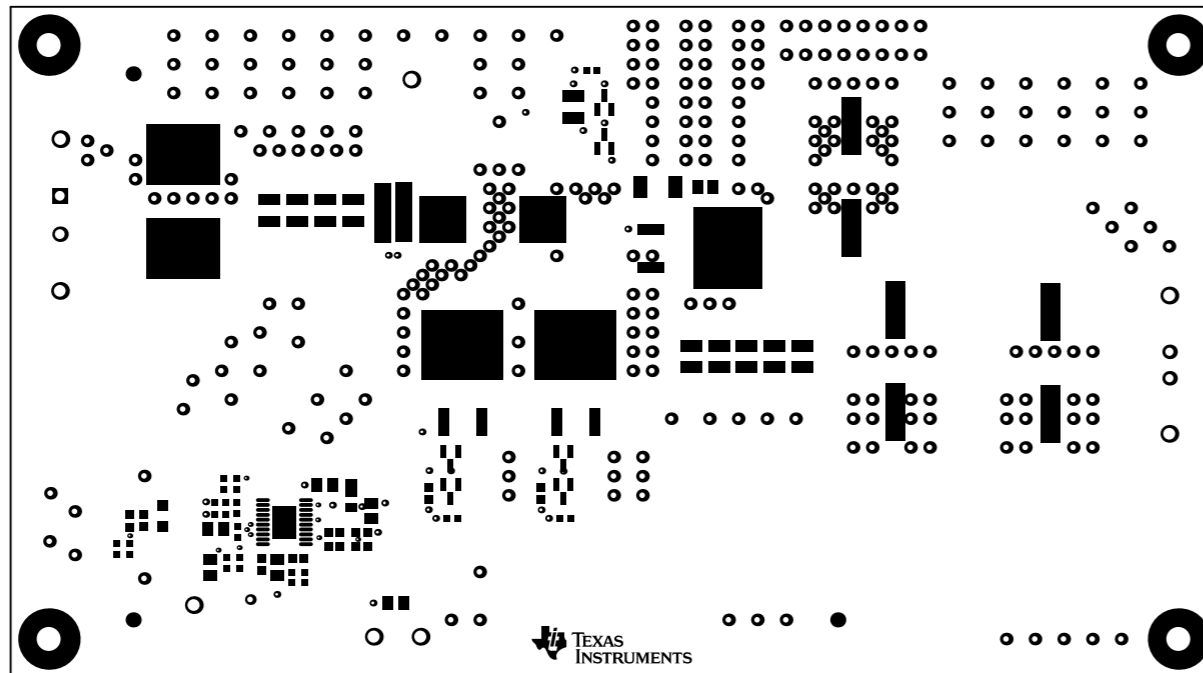
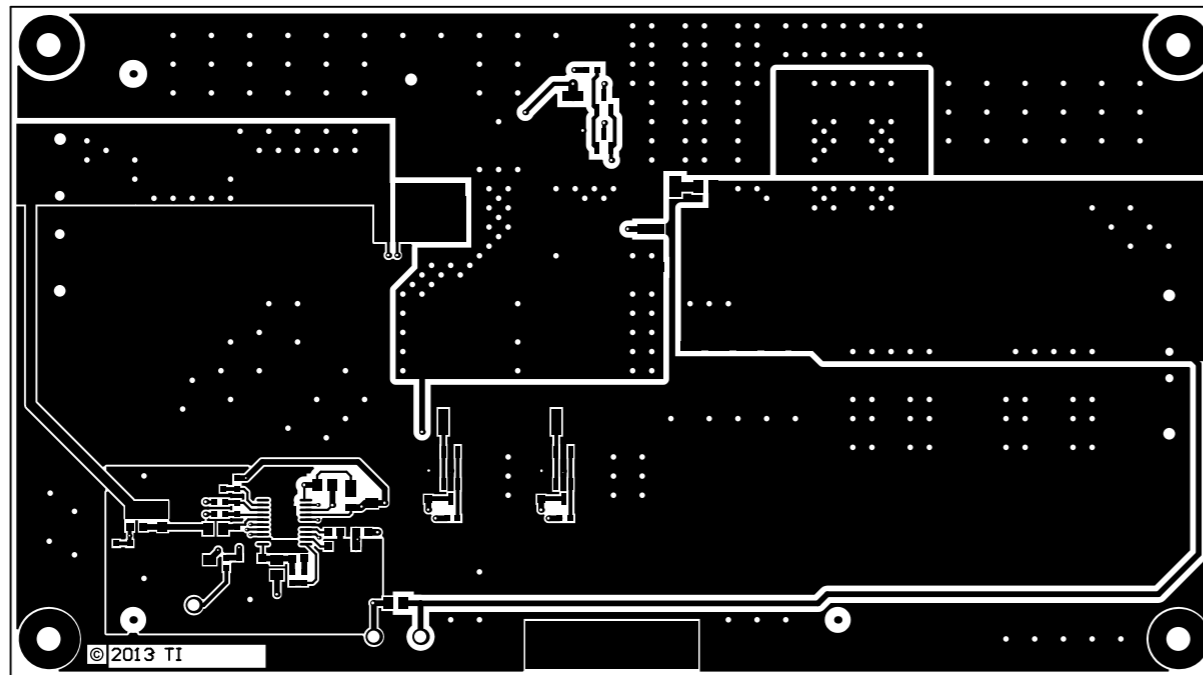


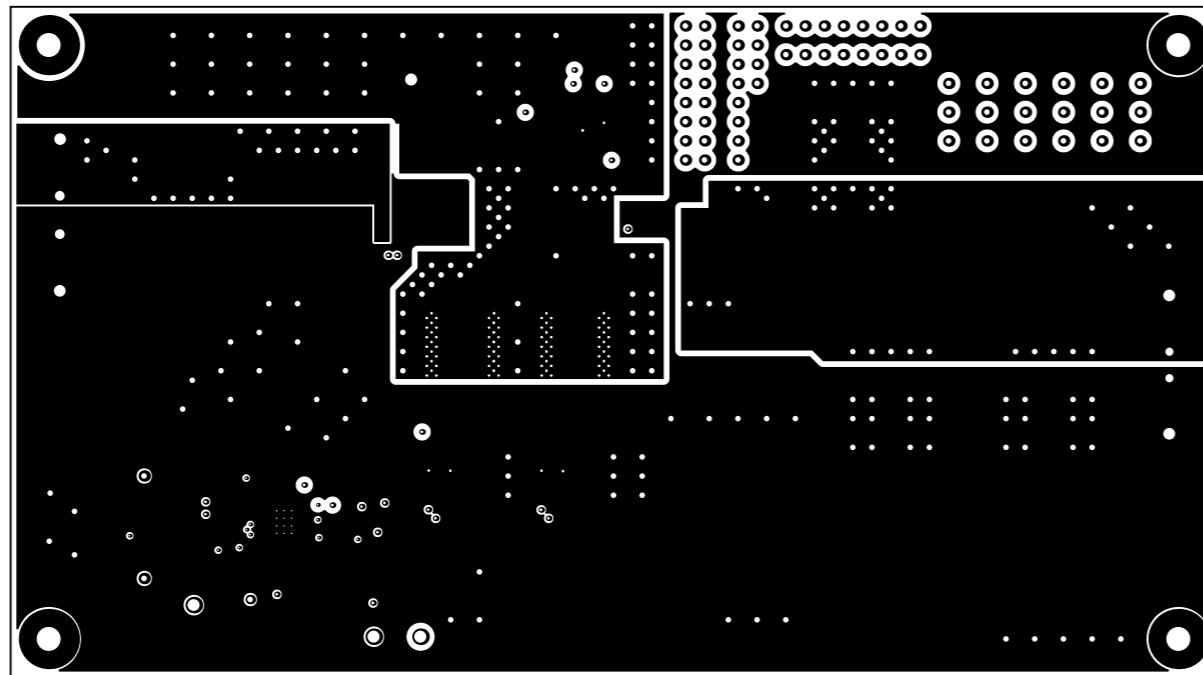
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7950	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 3/24/2015 1:53:28 PM	TEXAS INSTRUMENTS	



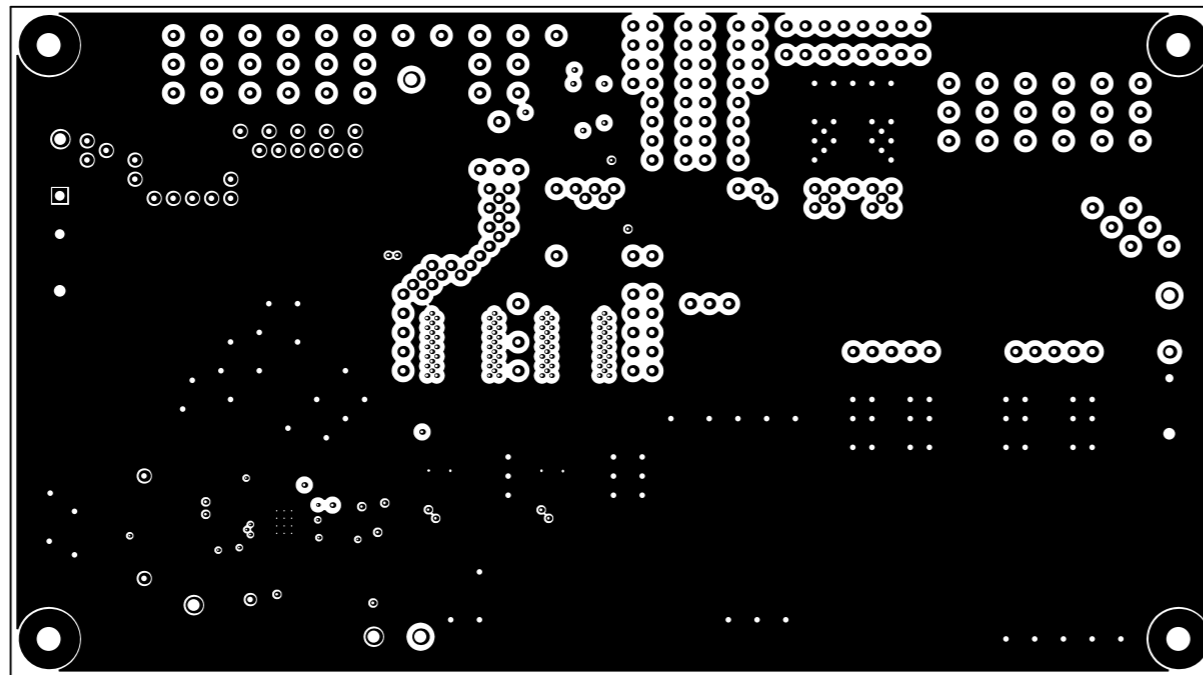
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7950	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 3/24/2015 1:53:29 PM	TEXAS INSTRUMENTS	



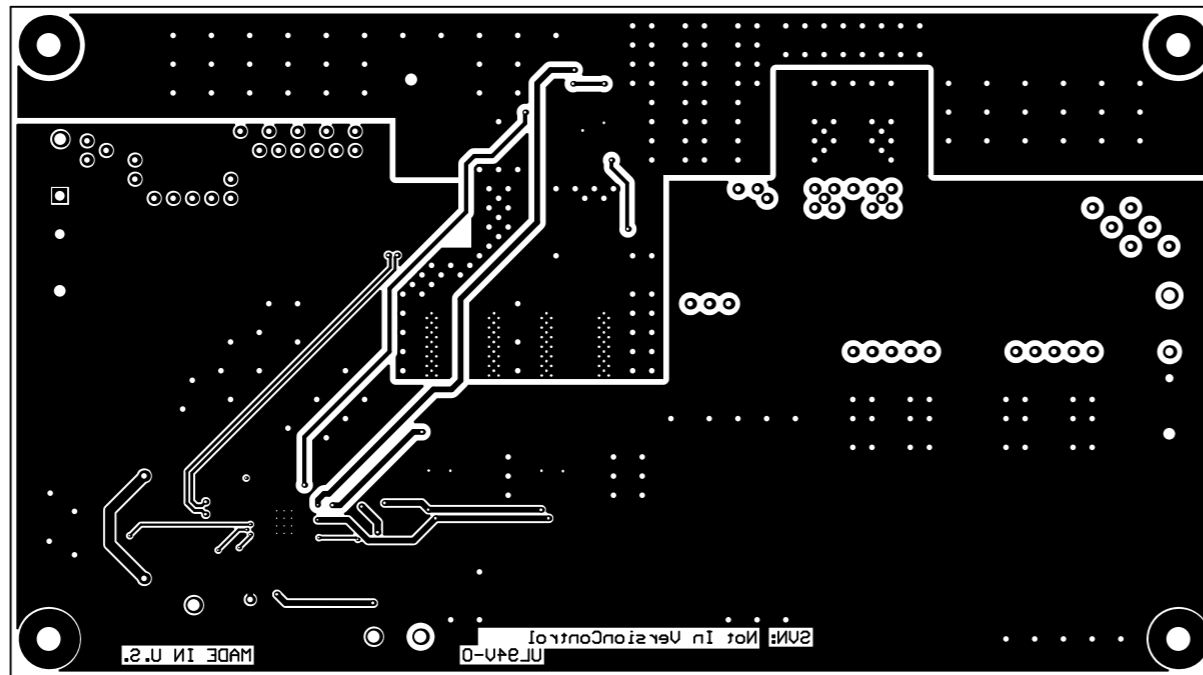
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7950	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 3/24/2015 1:53:29 PM	TEXAS INSTRUMENTS	



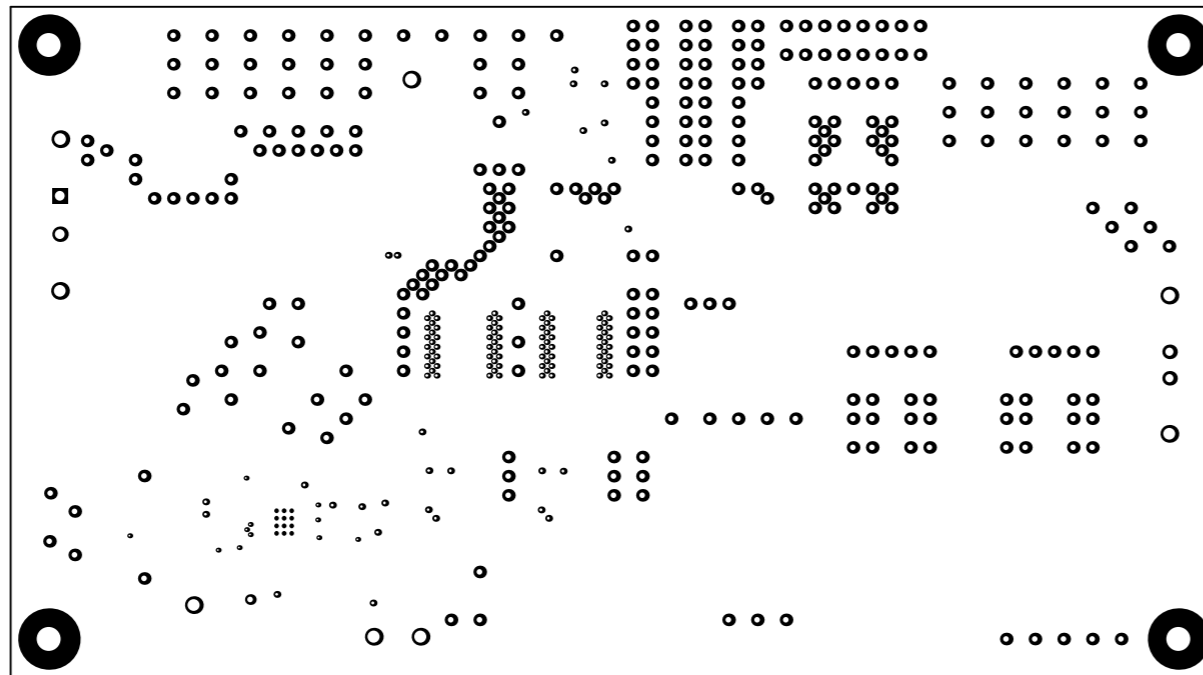
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7950	REV: B	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer1	GENERATED : 3/24/2015 1:53:30 PM	TEXAS INSTRUMENTS	



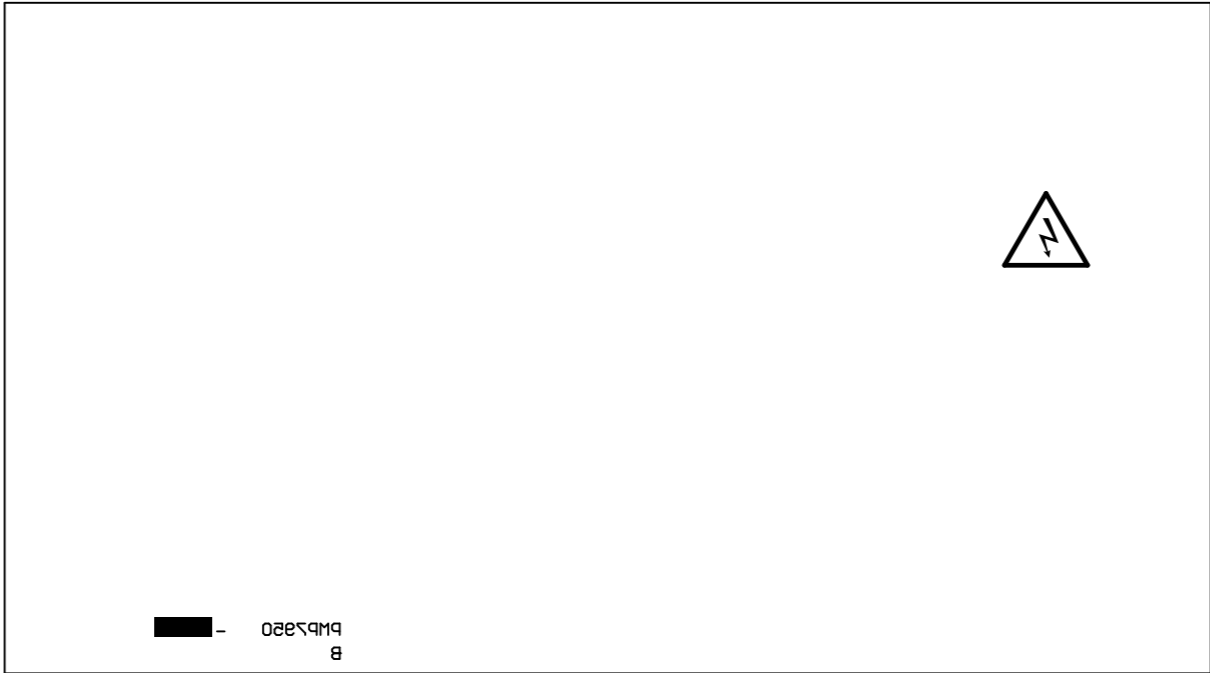
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7950	REV: B	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = MidLayer2	GENERATED : 3/24/2015 1:53:31 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7950	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 3/24/2015 1:53:32 PM	TEXAS INSTRUMENTS	



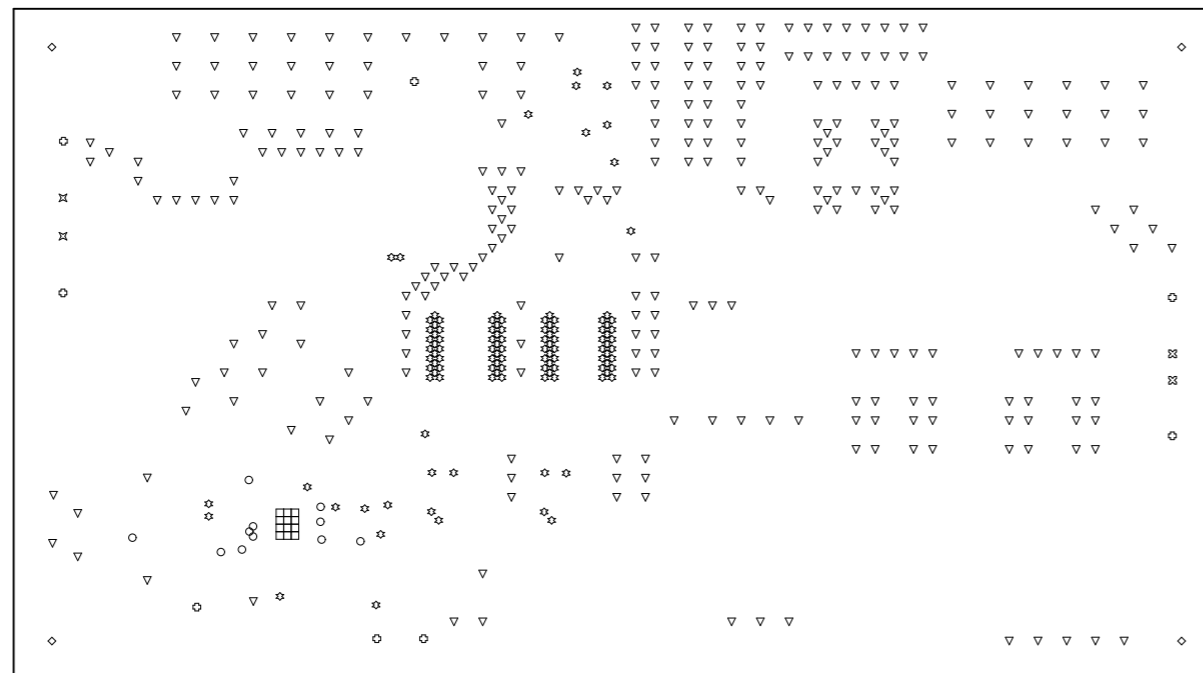
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7950	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 3/24/2015 1:53:32 PM	TEXAS INSTRUMENTS	



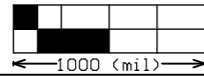
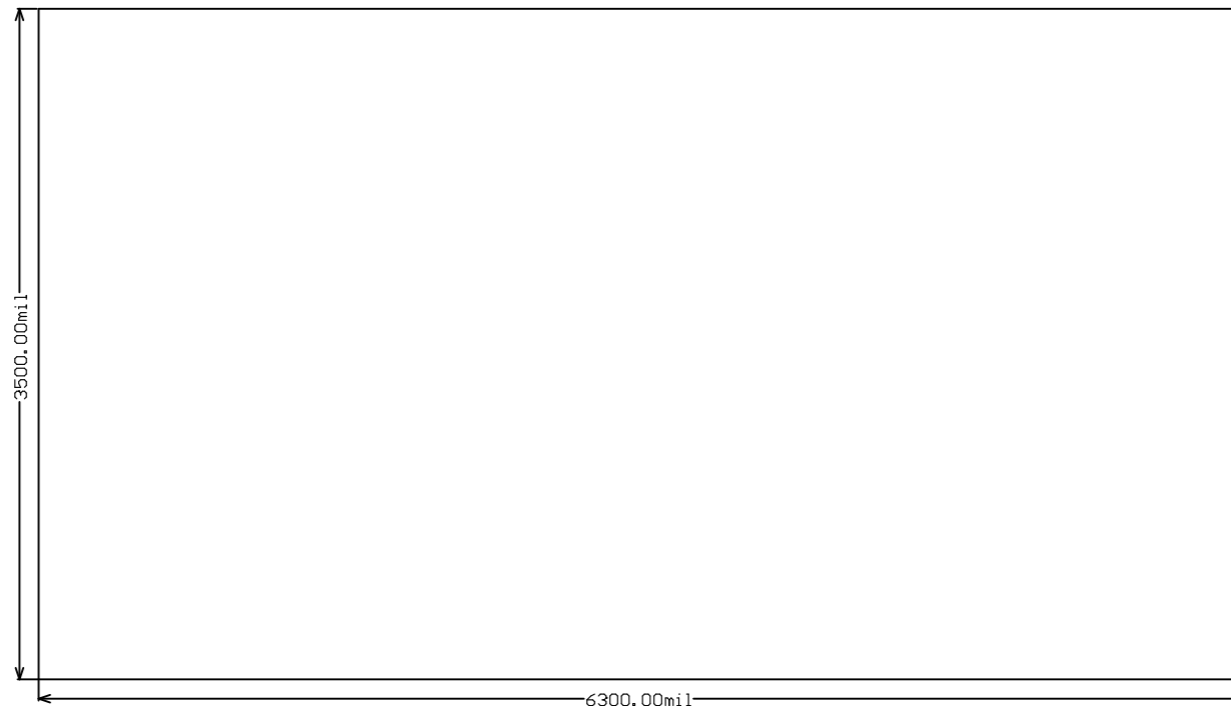
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7950	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 3/24/2015 1:53:33 PM	TEXAS INSTRUMENTS	

Symbol	Hit Count	Tool Size	Plated	Hole Type
□	12	7.874mil (0.2mm)	PTH	Round
○	11	10mil (0.254mm)	PTH	Round
*	112	15mil (0.381mm)	PTH	Round
▽	298	30mil (0.762mm)	PTH	Round
⊗	2	43.307mil (1.1mm)	PTH	Round
⊗	2	51.181mil (1.3mm)	PTH	Round
⊗	8	63mil (1.6mm)	PTH	Round
◇	4	125.984mil (3.2mm)	PTH	Round
	449 Total			

Drill Table



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7950	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 3/24/2015 1:53:34 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP7950	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 3/24/2015 1:53:35 PM	TEXAS INSTRUMENTS	

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